SCES397A-JULY 2002-REVISED AUGUST 2004

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- Ideal for Use in PC133 Register DIMM
- Typical Output Skew . . . <250 ps
- V_{CC} = 3.3 V \pm 0.3 V . . . Normal Range
- V_{CC} = 2.7 V to 3.6 V . . . Extended Range
- $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$
- Rail-to-Rail Output Swing for Increased Noise Margin
- Balanced Output Drivers . . . ±18 mA
- Low Switching Noise
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

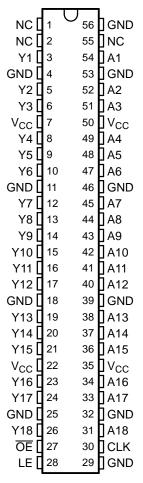
DESCRIPTION/ORDERING INFORMATION

This 18-bit universal bus driver is designed for 2.3-V to 3.6-V V_{CC} operation.

Data flow from A to Y is controlled by the output-enable (\overline{OE}) input. The device operates in the transparent mode when the latch-enable (LE) input is high. When LE is low, the A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When \overline{OE} is high, the outputs are in the high-impedance state.

The SN74ALVCF162835 has series damping resistors in the device output structure that reduce switching noise in 128-MB and 256-MB SDRAM modules. Designed with a drive capability of ± 18 mA, this device is a midway drive between the SN74ALVC162835 (± 12 mA) and SN74ALVC16835 (± 24 mA).

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SSOP - DL	Tube	SN74ALVCF162835DL	ALVCF162835	
400C to 050C	330P - DL	Tape and reel	SN74ALVCF162835DLR	ALVCF 102033	
-40°C to 85°C	TSSOP - DGG	Tape and reel	SN74ALVCF162835GR	ALVCF162835	
	TVSOP - DGV	Tape and reel	SN74ALVCF162835VR	VF2835	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The SN74ALVCF162835 is a faster version of the SN74ALVC162835. It is suitable for PC133 applications and, particularly, SDRAM modules clocked at 133 MHz.

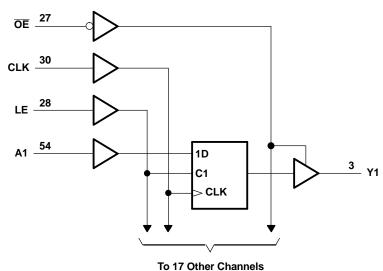
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

	INPUTS							
ŌĒ	LE	CLK	Α	Y				
Н	Х	Х	Х	Z				
L	Н	X	L	L				
L	Н	X	Н	н				
L	L	\uparrow	L	L				
L	L	\uparrow	Н	н				
L	L	L or H	Χ	Y ₀ ⁽¹⁾				

 Output level before the indicated steady-state input conditions were established

LOGIC DIAGRAM (POSITIVE LOGIC)





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ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			N	ΛIN	MAX	UNIT
V _{CC}	Supply voltage range				4.6	V
VI	Input voltage range ⁽²⁾		-	0.5	4.6	V
Vo	Output voltage range (2)(3)		-	0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	$V_1 < 0$ or $V_1 < V_{CC}$			-50	mA
I _{OK}	Output clamp current	V _O < 0			-50	mA
Io	Continuous output current	•			±50	mA
	Continuous current through each V _{CC} or 0	GND			±100	mA
		DGG package			64	
θ_{JA}	Package thermal impedance (4)	DGV package			48	°C/W
		DL package			56	
T _{stg}	Storage temperature range			-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
V _{IH}	r light-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
	Low level input voltage	Low-level input voltage		0.7	V
V_{IL}	Low-level input voltage $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$			0.8	V
V _I	Input voltage		0	V_{CC}	V
Vo	Output voltage		0	V_{CC}	V
		V _{CC} = 2.3 V		-6	
	High-level output current	VCC - 2.5 V		-8	
		V _{CC} = 2.7 V		-6	mA
I _{OH}		VCC - 2.7 V		-12	'''^
		V _{CC} = 3 V		-8	
		v _{CC} = 3 v		-18	
		V - 2.2.V		6	
		V _{CC} = 2.3 V		8	1
	Low level output ourrent	V - 27 V		6	mA
I _{OL}	Low-level output current	$V_{CC} = 2.7 \text{ V}$		12	
		V - 2 V		8	
		V _{CC} = 3 V		18	
Δt/Δν	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-40	85	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PAR	AMETER	TEST CONDIT	IONS	v _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT	
		I _{OH} = -0.1 mA		2.3 V to 3.6 V	V _{CC} - 0.2				
		I _{OH} = -6 mA		2.3 V	1.9				
		I _{OH} = -8 mA		2.3 V	1.7				
V _{OH}	V_{OH}	I _{OH} = -6 mA		2.7 V	2.2			V	
		I _{OH} = -12 mA		2.7 V	2				
		I _{OH} = -8 mA		3 V	2.4				
		I _{OH} = -18 mA	3 V	2					
		I _{OL} = 0.1 mA		2.3 V to 3.6 V			0.2		
		I _{OL} = 6 mA		221/			0.4		
		I _{OL} = 8 mA		2.3 V			0.55		
V _{OL}		I _{OL} = 6 mA	2.7 V			0.4	V		
		I _{OL} = 12 mA	2.7 V			0.6			
		I _{OL} = 8 mA	3 V			0.55			
		I _{OL} = 18 mA		3 V			0.8		
V _{IK}		$V_{CC} = 2.3 \text{ V}, \qquad \qquad I_{I} = -1$	8 mA	3.6 V			-1.2	V	
V _{hys}		V _{CC} = 3.6 V		3.6 V		100		mV	
I		V _I = V _{CC} or GND		3.6 V			±5	μΑ	
I _{OZ}		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
I _{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$)	3.6 V		0.1	40	μΑ	
ΔI_{CC}		One input at V _{CC} - 0.6 V, Other	r inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ	
C _i	Inputs	V _I = 0 V		3.3 V		3.5		pF	
C _o	Outputs	$V_O = 0 V$		3.3 V		4.5		pF	

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 and Figure 2)

				V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		$V V_{CC} = 3.3 V \pm 0.3 V$		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX		
f _{clock}	Clock frequency				150		150		150	MHz	
t Pulse duration		LE high	3.3		3.3		3.3		ns		
l t _w	Pulse duration	CLK high or low	3.3		3.3		3.3		115		
		Data before CLK↑		1.8		1.5		1			
t _{su}	Setup time	5.1.6.151		1.9		1.6		1.5		ns	
		Data before LE↓	CLK low	1.3		1.1		1		1	
	Hold time	Data after CLK↑		0.6		0.6		0.6			
t _h	noid time	Data after LE↓	CLK high or low	1.4		1.7		1.4		ns	



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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 and Figure 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = ± 0.2	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} = ± 0.3	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			150		150		150		MHz
	A		1	4		4.6	1	3.5	
t _{pd}	LE	Y	1.3	5.5		5.4	1.3	4.6	ns
·	CLK		1.4	5.9		5.6	1.4	3.5	
t _{en}	ŌĒ	Y	1.4	5.9	-	6	1.1	5	ns
t _{dis}	ŌĒ	Y	1	4.7	-	4.6	1.3	4.2	ns
t _{sk(o)}								500	ps

SWITCHING CHARACTERISTICS

from 0° C to 65° C, $C_{L} = 50 \text{ pF}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1	UNIT	
	(INFOT)	(001701)	MIN	MAX	
t _{pd}	CLK	Υ	1.8	3.5	ns

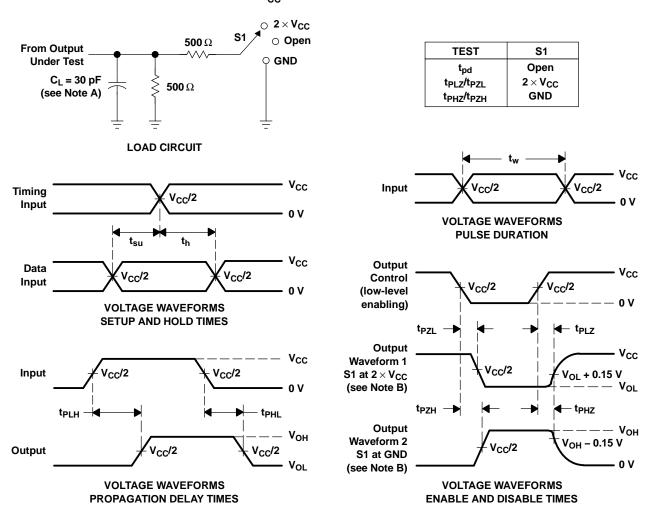
OPERATING CHARACTERISTICS

 $T_A = 25^{\circ}C$

	PARAMETER			NDITIONS	V _{CC} = 2.5 V V _{CC} = 3.3 V		UNIT	
				NDITIONS	TYP	TYP	UNIT	
	Dower dissinction consistence	Outputs enabled	C 0.5F	f 10 MHz	27	33	ړ	
١	Power dissipation capacitance	Outputs disabled	$C_L = 0 pF,$	f = 10 MHz	16	21	pF	



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V

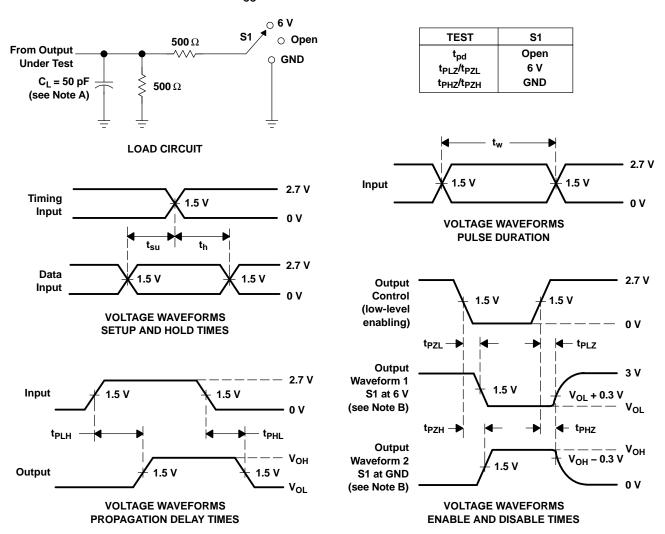


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z $_{O}$ = 50 $\Omega,\,t_{f}$ \leq 2 ns, t_{f} \leq 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. $t_{Pl,7}$ and t_{PH7} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_0 = 50 Ω , $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVCF162835GRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCF162835VRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCF162835DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCF162835GR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCF162835LR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCF162835VR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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